

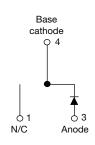
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Vishay Semiconductors

HALOGEN

Ultrafast Rectifier, 30 A FRED Pt®





D ² PAK	2L ((TO-263AB 2	L)

DDIMARY CHARACTERISTICS								
PRIMARY CHARACTE	PRIMARY CHARACTERISTICS							
$I_{F(AV)}$	30 A							
V_{R}	600 V							
V _F at I _F	1.15 V							
t _{rr} (typ.)	30 ns							
T_J max.	175 °C							
Package	D ² PAK 2L (TO-263AB 2L)							
Circuit configuration	Single							

FEATURES

- Low forward voltage drop
- · Ultrafast recovery time
- 175 °C operating junction temperature
- · Low leakage current
- FREE AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

Ultralow V_F, soft-switching ultrafast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

MECHANICAL DATA

Case: D²PAK 2L (TO-263AB 2L)

Molding compound meets UL 94 V-0 flammability rating Terminals: matte tin plated leads, solderable per

J-STD-002

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS				
Repetitive peak reverse voltage	V_{RRM}		600	V				
Average rectified forward current	I _{F(AV)}	T _C = 122 °C	30	Δ.				
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	200	Α				
Operating junction and storage temperatures	T _J , T _{Sta}		-55 to +175	°C				

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-	.,		
Forward voltage	V _F	I _F = 30 A	-	1.4	2.0	V		
		I _F = 30 A, T _J = 150 °C	-	1.15	1.35			
Dovorgo lookago ourrent		$V_R = V_R$ rated	-	0.02	30			
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	30	250	μA		
Junction capacitance	C _T	V _R = 600 V	-	20	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	1	nΗ		



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 \text{ A}, dI_F/dt = 50$	$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		30	-		
Reverse recovery time	t _{rr}	T _J = 25 °C	I _F = 30 A dI _F /dt = 200 A/μs V _R = 200 V	-	45	-	ns A nC	
		T _J = 125 °C		-	100	-		
Dook recovery current	I _{RRM}	T _J = 25 °C		-	5.6	-		
Peak recovery current		T _J = 125 °C		-	10	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	127	-		
		T _J = 125 °C		-	580	-		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C		
Thermal resistance, junction-to-case	R _{thJC}		-	0.95	1.2	°C/W		
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70			
Thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-			
Weight			-	2.0	-	g		
vveignt			-	0.07	-	oz.		
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style D ² PAK 2L (TO-263AB 2L)	ETU3006SH					

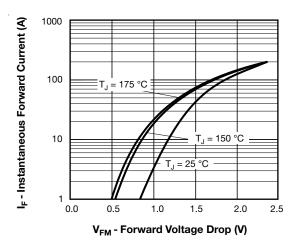


Fig. 1 - Typical Forward Voltage Drop Characteristics

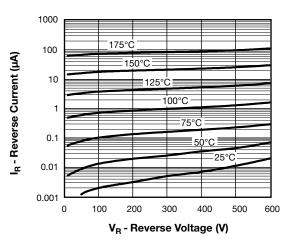


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

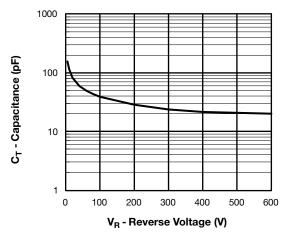


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

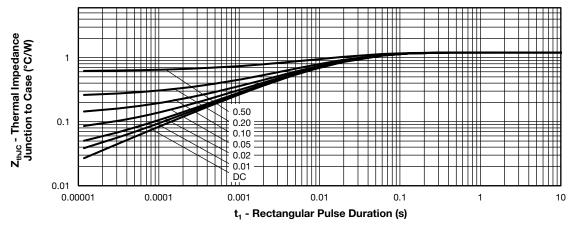


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

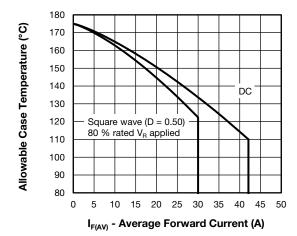


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

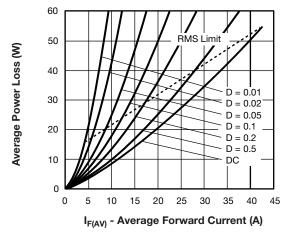


Fig. 6 - Forward Power Loss Characteristics



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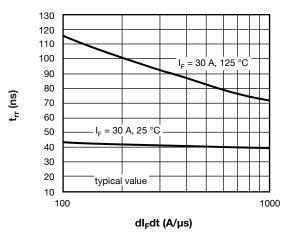


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

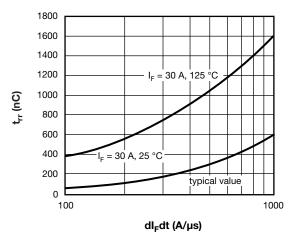
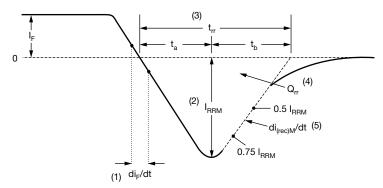


Fig. 8 - Typical Stored Charge vs. dl_E/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{rr}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

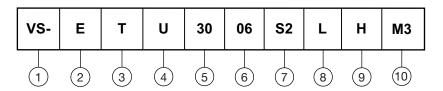
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Circuit configuration

E = single

 $T = D^2PAK (TO-262) package$

U = ultrafast recovery time

- Current code (30 = 30 A)

6 - Voltage code (06 = 600 V)

 $\overline{7}$ - S2 = true 2 pin D²PAK

8 - • None = tube

L = tape and reel (left oriented, for D²PAK package)
If needed different orientation/packaging, please contact factory

9 - H = AEC-Q101 qualified

10 - Environmental digit:

M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

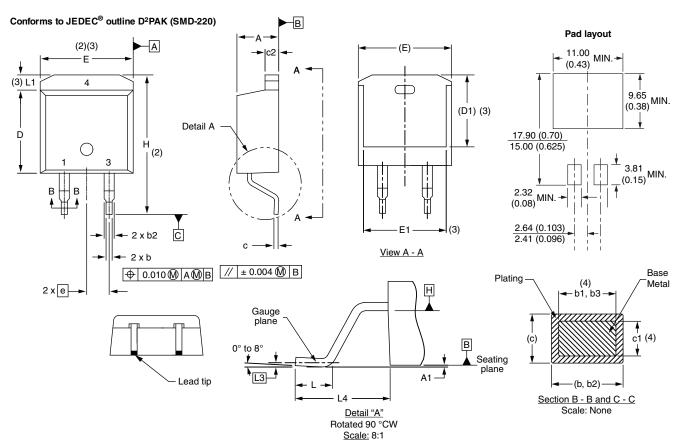
ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-ETU3006S2LHM3	800	800	13" diameter reel				

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96683				
Part marking information	www.vishay.com/doc?96693				
Packaging information	www.vishay.com/doc?95032				
SPICE model	www.vishay.com/doc?96775				



2L-D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	MILLIMETERS		INCHES	
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INCHES		NOTES	
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.100 BSC			
Н	14.61	15.88	0.575	0.625		
L	1.78	2.79	0.070	0.110		
L1	-	1.65	-	0.066	3	
L3	0.25 BSC		0.010) BSC		
L4	4.78	5.28	0.188	0.208		

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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